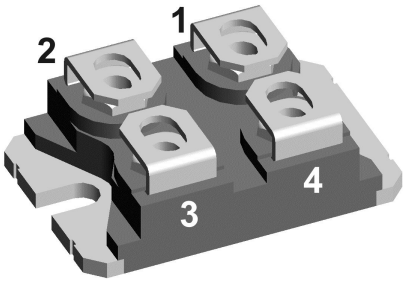
HiPerFRED

V_{RRM}	=	300 V
I_{FAV}	= 2x	90 A
t_{rr}	=	30 ns

High Performance Fast Recovery Diode
Low Loss and Soft Recovery
Parallel legs

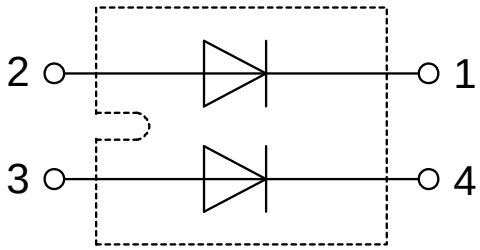
Part number

DSEP2x91-03A



Backside: isolated

E72873



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low Irm-values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low Irm reduces:
  - Power dissipation within the diode
  - Turn-on loss in the commutating switch

Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package: SOT-227B (minibloc)

- Isolation Voltage: 3000 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Base plate: Copper internally DCB isolated
- Advanced power cycling

Terms _Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact your local sales office.
Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact your local sales office.
Should you intend to use the product in aviation, in health or life endangering or life support applications, please notify. For any such application we urgently recommend
- to perform joint risk and quality assessments;
- the conclusion of quality agreements;
- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, conditions and dimensions. Data according to IEC 60747and per semiconductor unless otherwise specified 20160920b

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Fast Diode				Ratings			
Symbol	**Definition**	**Conditions**		**min.**	**typ.**	**max.**	**Unit**
V_{RSM}	*max. non-repetitive reverse blocking voltage*		T_{VJ} = 25°C			300	V
V_{RRM}	*max. repetitive reverse blocking voltage*		T_{VJ} = 25°C			300	V
I_R	*reverse current, drain current*	V_R = 300 V	T_{VJ} = 25°C			1	mA
		V_R = 300 V	T_{VJ} = 150°C			4	mA
V_F	*forward voltage drop*	I_F = 90 A	T_{VJ} = 25°C			1.54	V
		I_F = 180 A				1.86	V
		I_F = 90 A	T_{VJ} = 150°C			1.10	V
		I_F = 180 A				1.44	V
I_{FAV}	*average forward current*	T_C = 75°C	T_{VJ} = 150°C			90	A
		rectangular d = 0.5					
V_{F0}	*threshold voltage* } *for power loss calculation only*		T_{VJ} = 150°C			0.77	V
r_F	*slope resistance* }					3.7	mΩ
R_{thJC}	*thermal resistance junction to case*					0.6	K/W
R_{thCH}	*thermal resistance case to heatsink*				0.10		K/W
P_{tot}	*total power dissipation*		T_C = 25°C			200	W
I_{FSM}	*max. forward surge current*	t = 10 ms; (50 Hz), sine; V_R = 0 V	T_{VJ} = 45°C			1.00	kA
C_J	*junction capacitance*	V_R = 150 V f = 1 MHz	T_{VJ} = 25°C		273		pF
I_{RM}	*max. reverse recovery current*		T_{VJ} = 25 °C		12		A
		I_F = 90 A; V_R = 150 V	T_{VJ} = 100 °C		15		A
t_{rr}	*reverse recovery time*	$-di_F/dt$ = 600 A/µs	T_{VJ} = 25 °C		40		ns
			T_{VJ} = 100 °C		60		ns

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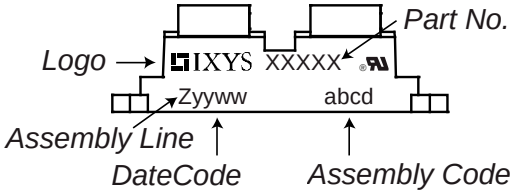
Package SOT-227B (minibloc)					Ratings			
Symbol	**Definition**	**Conditions**			**min.**	**typ.**	**max.**	**Unit**
I_{RMS}	*RMS current*	per terminal					100	A
T_{VJ}	*virtual junction temperature*				-40		150	°C
T_{op}	*operation temperature*				-40		125	°C
T_{stg}	*storage temperature*				-40		150	°C
Weight						30		g
M_D	*mounting torque*				1.1		1.5	Nm
M_T	*terminal torque*				1.1		1.5	Nm
$d_{Spp/App}$	*creepage distance on surface | striking distance through air*		*terminal to terminal*	10.5	3.2			mm
$d_{Spb/Apb}$			*terminal to backside*	8.6	6.8			mm
V_{ISOL}	*isolation voltage*	t = 1 second	50/60 Hz, RMS; I_{ISOL} ≤ 1 mA		3000			V
		t = 1 minute			2500			V

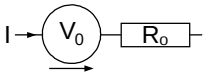
Product Marking



Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DSEP2x91-03A	DSEP2x91-03A	Tube	10	476269

Equivalent Circuits for Simulation

** on die level* T_{VJ} = 150 °C



		Fast Diode	
$V_{0\ max}$	*threshold voltage*	0.77	V
$R_{0\ max}$	*slope resistance **	1.8	mΩ

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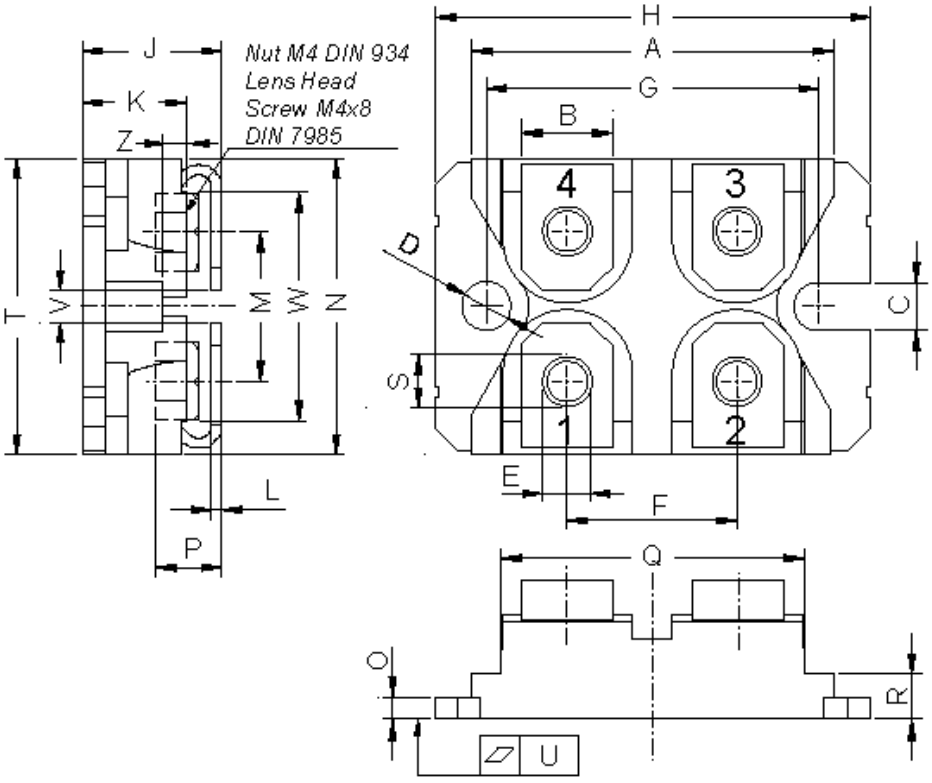
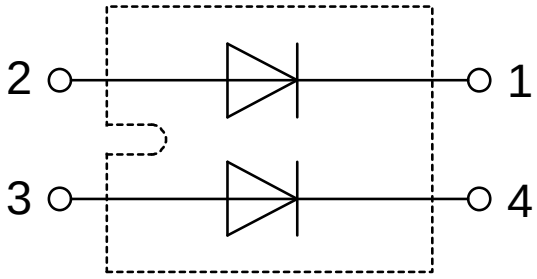
Outlines SOT-227B (minibloc)



Dim.	Millimeter		Inches	
	min	max	min	max
A	31.50	31.88	1.240	1.255
B	7.80	8.20	0.307	0.323
C	4.09	4.29	0.161	0.169
D	4.09	4.29	0.161	0.169
E	4.09	4.29	0.161	0.169
F	14.91	15.11	0.587	0.595
G	30.12	30.30	1.186	1.193
H	37.80	38.23	1.488	1.505
J	11.68	12.22	0.460	0.481
K	8.92	9.60	0.351	0.378
L	0.74	0.84	0.029	0.033
M	12.50	13.10	0.492	0.516
N	25.15	25.42	0.990	1.001
O	1.95	2.13	0.077	0.084
P	4.95	6.20	0.195	0.244
Q	26.54	26.90	1.045	1.059
R	3.94	4.42	0.155	0.167
S	4.55	4.85	0.179	0.191
T	24.59	25.25	0.968	0.994
U	-0.05	0.10	-0.002	0.004
V	3.20	5.50	0.126	0.217
W	19.81	21.08	0.780	0.830
Z	2.50	2.70	0.098	0.106



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Fast Diode

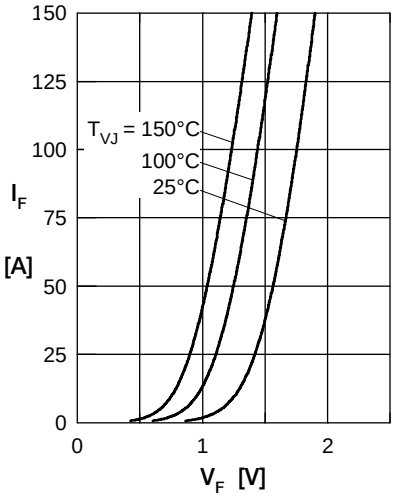

Fig. 1 Forward current I_F versus V_F

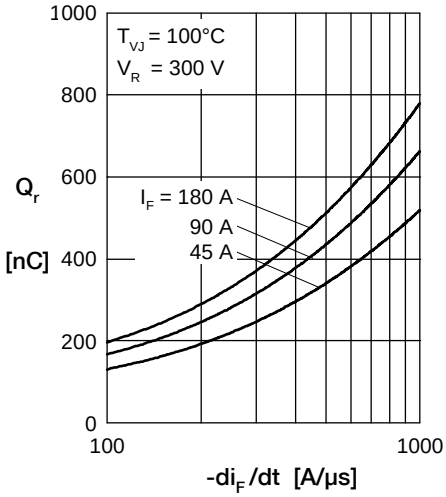

Fig. 2 Typ. reverse recov. charge Q_r versus -di$_F$/dt

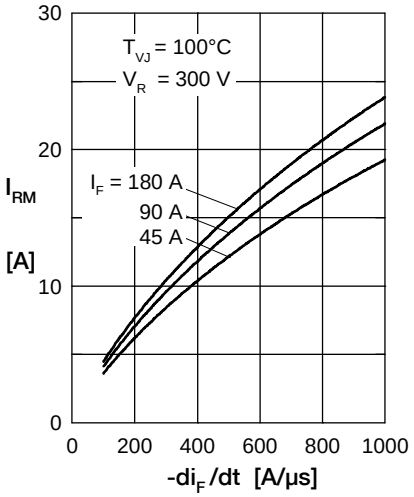

Fig. 3 Typ. peak reverse current I_{RM} versus -di$_F$/dt

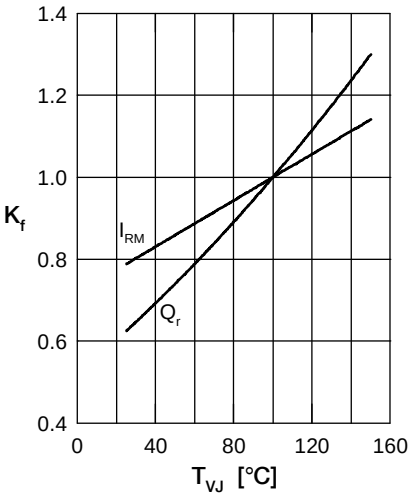

Fig. 4 Dynamic parameters Q_r, I_{RM} versus T_{VJ}

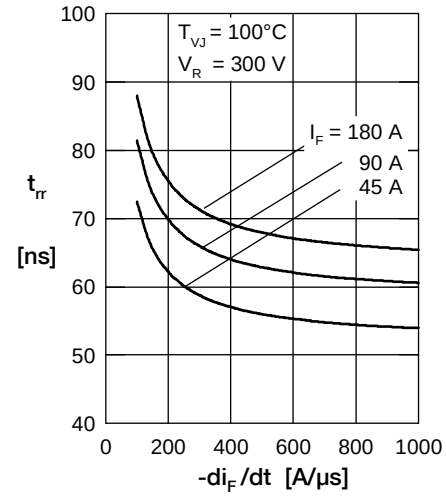

Fig. 5 Recovery time t_{rr} versus -di$_F$/dt

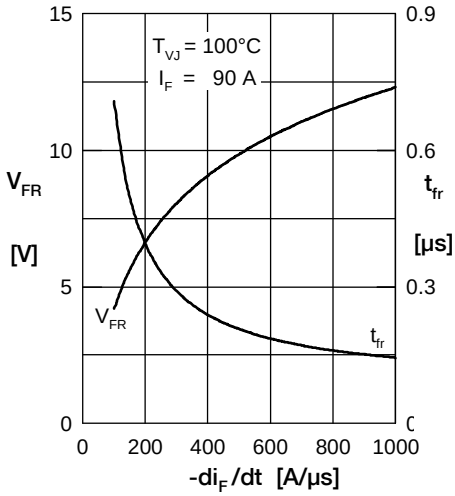

Fig. 6 Peak forward voltage V_{FR} and tfr versus di$_F$/dt

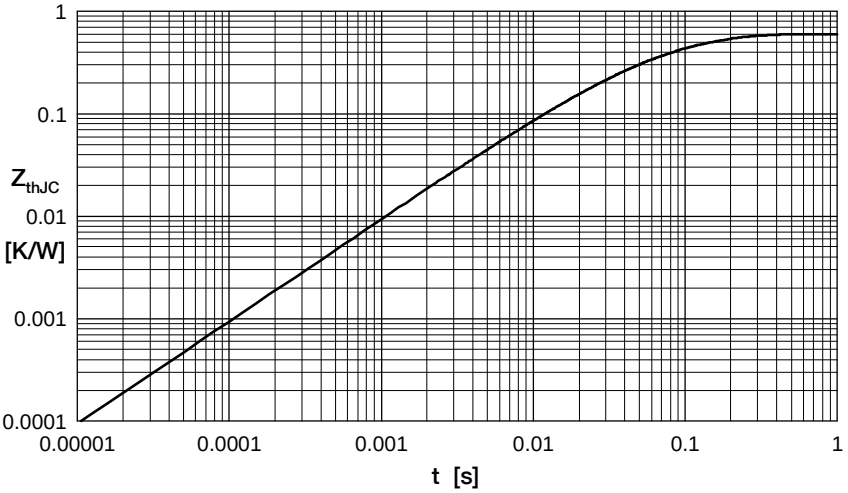

Fig. 7 Transient thermal resistance junction to case

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.212	0.0055
2	0.248	0.0092
3	0.063	0.0007
4	0.077	0.0391

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